

Using the TPS54291EVM-431 A 12V Input, 3.3V 1.5A and 1.2V 2.5A Synchronous Buck Converter

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1 Introduction

The TPS54291EVM-431 evaluation module (EVM) is a dual synchronous buck converter providing fixed 3.3V and 1.2V outputs at up to 1.5A and 2.5A respectively from a 12V bus. The EVM is designed to start-up from a single supply, so no additional bias voltages are require for start-up. The module uses the TPS54291 600kHz Dual Synchronous Buck Converter with integral MOSFETs.

1.1 Description

TPS54291EVM-431 is designed to use a regulated 12V (+10% /–20%) bus to produce two regulated power rails, 3.3V at 1.5A and 1.2V at 2.5A. TPS54291EVM-431 is designed to demonstrate the TPS54291 in a typical 12-V bus system while providing a number of test points to evaluate the performance of the TPS54291 in a given application. The EVM can be modified to other output voltages by changing some of the components.

1.2 Applications

- Non-Isolated Point of Load and Voltage bus converters.
- Consumer Electronics
- LCD TV
- Computer Peripherals
- Digital Set Top Box

1.3 Features

- 12 V +10% /–20% input range
- 5.0 V and 3.3 V fixed output voltage, adjustable with resistor change
- 1.5A (3.3V) and 2.5A (1.2V) Steady State Current
- 600kHz switching frequency (Fixed by TPS54291)
- Internal switching MOSFET and external Rectifier Diode.
- Double Sided 2 Active Layer PCB with all components on top side (Test Point signals routed on internal layers)
- Active Converter area of 1.1 square inches (0.86" × 1.28")
- Convenient test points for probing switching waveforms and non-invasive loop response testing

2 TPS54291EVM-431 Electrical Performance Specifications

Table 1. TPS54291EVM-431 Electrical and Performance Specifications

Parameter	Notes and Conditions	Min	Nom	Max	Units
INPUT CHARACTERISTICS					
V_{IN} Input Voltage		9.6	12	13.2	V
I_{IN} Input Current	$V_{IN} = \text{Nom}$, $I_{OUT} = \text{Max}$	–	2.4	2.6	A
No Load Input Current	$V_{IN} = \text{Nom}$, $I_{OUT} = 0 \text{ A}$	–	12	20	mA
V_{IN_UVLO} Input UVLO	$I_{OUT} = \text{Min to Max}$	4.0	4.2	4.4	V
OUTPUT CHARACTERISTICS					
V_{OUT1} Output Voltage 1	$V_{IN} = \text{Nom}$, $I_{OUT} = \text{Nom}$	3.20	3.30	3.40	V
V_{OUT2} Output Voltage 2	$V_{IN} = \text{Nom}$, $I_{OUT} = \text{Nom}$	1.15	1.20	1.25	V
Line Regulation	$V_{IN} = \text{Min to Max}$	–	–	1%	
Load Regulation	$I_{OUT} = \text{Min to Max}$	–	–	1%	
V_{OUT_ripple} Output Voltage Ripple	$V_{IN} = \text{Nom}$, $I_{OUT} = \text{Max}$	–	–	50	mVpp
I_{OUT1} Output Current 1	$V_{IN} = \text{Min to Max}$	0		2.5	A
I_{OUT2} Output Current 2	$V_{IN} = \text{Min to Max}$	0		2.5	A
I_{OCP1} Output Over Current Channel 1	$V_{IN} = \text{Nom}$, $V_{OUT} = V_{OUT1} - 5\%$	1.6	2.0	2.4	A
I_{OCP2} Output Over Current Channel 2	$V_{IN} = \text{Nom}$, $V_{OUT} = V_{OUT2} - 5\%$	3.0	3.6	4.4	A
SYSTEMS CHARACTERISTICS					
F_{SW} Switching Frequency		520	600	720	kHz
η_{pk} Peak Efficiency	$V_{IN} = \text{Nom}$	–	88%	–	
η Full Load Efficiency	$V_{IN} = \text{Nom}$, $I_{OUT1} = I_{OUT1} = \text{Max}$	–	85%	–	
Top Operating Temperature Range	$V_{IN} = \text{Min to Max}$, $I_{OUT} = \text{Min to Max}$	0	25	60	°C

3 Schematic

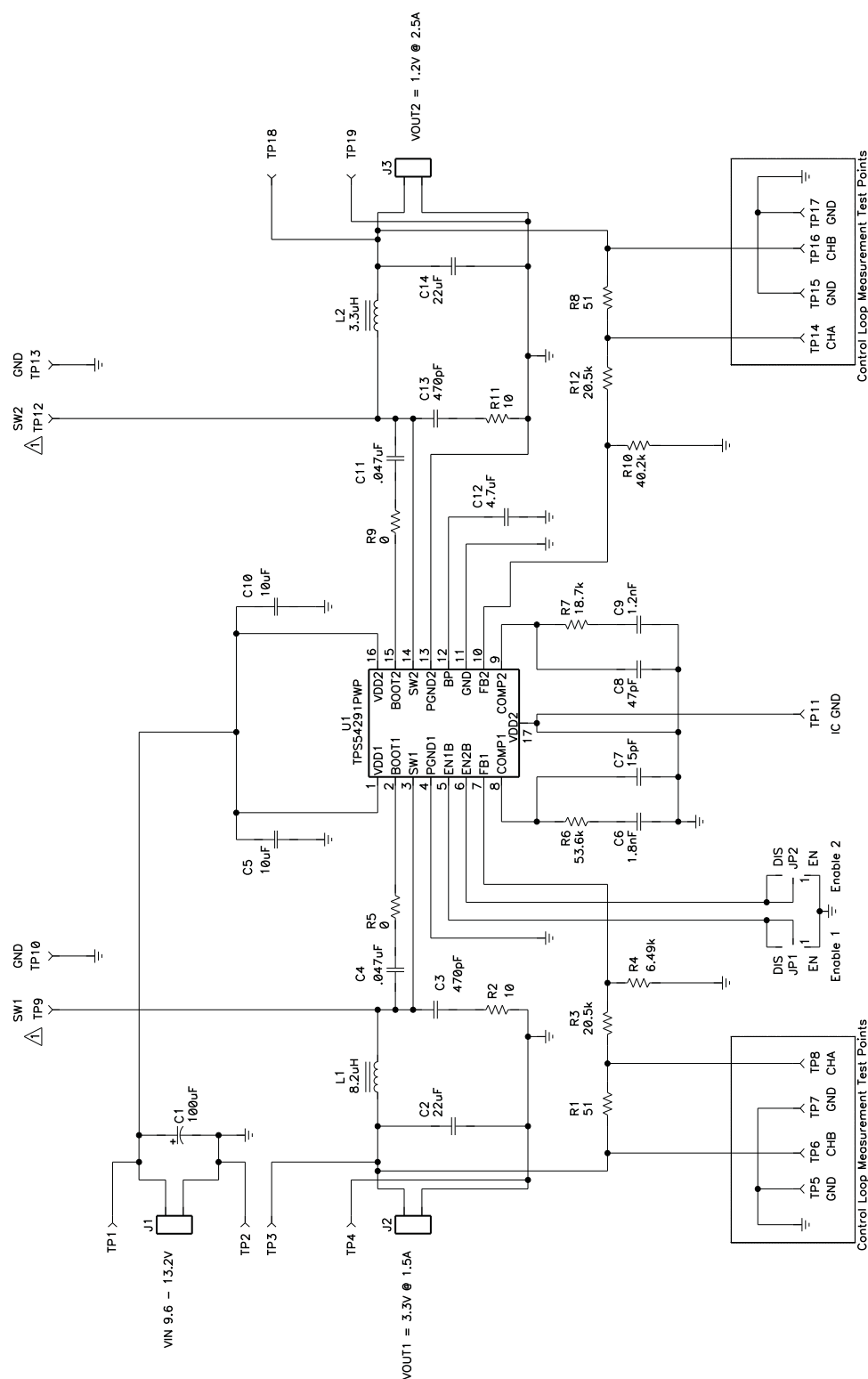


Figure 1. TPS54291EVM-431 Schematic
(For Reference Only, See Table 4: Bill of Materials for Specific Values)

3.1 Enable Jumpers (JP1 and JP2)

TPS54291EVM-431 provides separate 3 pin 100-mil headers and shunts for exercising the TPS54291 Enable functions. Place the JP1 shunt in the Left Position connects EN1 to ground and turns on Output 1 and placing the JP2 shunt in the Left Position connects EN2 to ground and turns on Output 2.

3.2 Error Amplifier Outputs

The output of the TPS54291 transconductance error amplifiers (COMP1 and COMP2) are sensitive to capacitive loading, including the typical 8-15pF capacitance added by an oscilloscope probe. No direct measurements of these signals should be attempted without using an external buffer to prevent loading of the control voltage.

3.3 Test Point Descriptions

Table 2. Test Point Descriptions

Test Point	Label	Use	Section
TP1	VIN	Monitor Input Voltage	3.3.1
TP2	GND	Ground for Input Voltage	3.3.1
TP3	VOUT1	Monitor VOUT1 Voltage	3.3.2
TP4	GND	Ground for VOUT1 Voltage	3.3.2
TP5	GND	Ground for VOUT1 Channel B Loop Monitoring	3.3.3
TP6	CHB	VOUT1 Channel B for Loop Monitoring	3.3.3
TP7	GND	Ground for VOUT1 Channel A Loop Monitoring	3.3.3
TP8	CHA	VOUT1 Channel B for Loop Monitoring	3.3.3
TP9	SW1	Monitor Switching Node of Channel 1	3.3.4
TP10	GND	Ground for Switch Node of Channel 1	3.3.4
TP11	IC_GND	Monitor IC Ground	3.3.5
TP12	SW2	Monitor Switching Node of Channel 2	3.3.6
TP13	GND	Ground for Switch Node of Channel 2	3.3.6
TP14	CHA	VOUT2 Channel A for Loop Monitoring	3.3.7
TP15	GND	Ground for VOUT2 Channel A Loop Monitoring	3.3.7
TP16	CHB	VOUT2 Channel B for Loop Monitoring	3.3.7
TP17	GND	Ground for VOUT2 Channel B Loop Monitoring	3.3.7
TP18	VOUT2	Monitor VOUT2 Voltage	3.3.8
TP19	GND	Ground for VOUT2 Voltage	3.3.8

3.3.1 Input Voltage Monitoring (TP1 and TP2)

TPS54291EVM-431 provides two test points for measuring the voltage applied to the module. This allows the user to measure the actual module voltage without losses from input cables and connectors. All input voltage measurements should be made between TP1 and TP2. To use TP1 and TP2, connect a voltmeter positive terminal to TP1 and negative terminal to TP2.

3.3.2 Channel 1 Output Voltage Monitoring (TP3 and TP4)

TPS54291EVM-431 provides two test points for measuring the voltage generated by the module. This allows the user to measure the actual module output voltage without losses from output cables and connectors. All output voltage measurements should be made between TP3 and TP4. To use TP3 and TP4, connect a voltmeter positive terminal to TP3 and negative terminal to TP4. For Output ripple measurements, TP3 and TP4 allow a user to limit the ground loop area by using the Tip and Barrel measurement technique shown in Figure 3. All output ripple measurements should be made using the Tip and Barrel measurement. . Even this Tip and Barrel measurement technique increases the measured switch edge noise. For improved output ripple measurement, measure the output ripple at the output capacitor (C5)

3.3.3 Channel 1 Loop Analysis (TP5, TP6, TP7 and TP8)

TPS54291EVM-431 contains a 51Ω series resistor (R1) in the feedback loop to allow for matched impedance signal injection into the feedback for loop response analysis. An isolation transformer should be used to apply a small (30mV or less) signal across R1 through TP6 and TP8. By monitoring the AC injection level at TP8 and the returned AC level at TP6, the power supply loop response can be determined.

3.3.4 Channel 1 Switching Waveforms (TP9 and TP10)

TPS54291EVM-431 provides a surface test pad and a local ground connection (TP10) for the monitoring of the channel 1 power stage switching waveform. Connect an Oscilloscope probe to TP9 to monitor the Switch Node voltage for channel 1. Test pads are used on the switch nodes to minimize radiated noise from the switch node.

3.3.5 TPS54291 IC Ground (TP11)

TPS54291EVM-431 provides a test point for the IC ground. To measure IC pin voltages, connect the ground of the oscilloscope probe to TP11.

3.3.6 Channel 2 Switching Waveforms (TP12 and TP13)

TPS54291EVM-431 provides a surface test pad and a local ground connection (TP13) for the monitoring of the channel 1 power stage switching waveform. Connect an Oscilloscope probe to TP12 to monitor the Switch Node voltage for channel 1. Test pads are used on the switch nodes to minimize radiated noise from the switch node.

3.3.7 Channel 2 Loop Analysis (TP14, TP15, TP16 and TP17)

TPS54291EVM-431 contains a 51Ω series resistor (R13) in the feedback loop to allow for matched impedance signal injection into the feedback for loop response analysis. An isolation transformer should be used to apply a small (30mV or less) signal across R13 through TP14 and TP16. By monitoring the AC injection level at TP14 and the returned AC level at TP16, the power supply loop response can be determined.

3.3.8 Output Voltage Monitoring (TP18 and TP19)

TPS54291EVM-431 provides two test points for measuring the voltage generated by the module. This allows the user to measure the actual module output voltage without losses from output cables and connector losses. All output voltage measurements should be made between TP18 and TP19. To use TP18 and TP19, connect a voltmeter positive terminal to TP18 and negative terminal to TP19. For Output ripple measurements, TP18 and TP19 allow a user to limit the ground loop area by using the Tip and Barrel measurement technique shown in [Figure 3](#). All output ripple measurements should be made using the Tip and Barrel measurement. Even this Tip and Barrel measurement technique increases the measured switch edge noise. For improved output ripple measurement, measure the output ripple at the output capacitor (C17).

4 Test Set UP

4.1 Equipment

4.1.1 Voltage Source

V_{IN}
The input voltage source (V_{IN}) should be a 0-15V variable DC source capable of 2A_{dc}. Connect V_{IN} to J1 as shown in [Figure 3](#).

4.1.2 Meters

A1: 0-2A_{dc}, ammeter

V1: VIN, 0-15V voltmeter
V2: VOUT1 0-6V voltmeter
V3: VOUT2 0-4V voltmeter

4.1.3 Loads

LOAD1

The Output1 Load (LOAD1) should be an Electronic Constant Current Mode Load capable of 0-1.5Adc at 3.3V

LOAD2

The Output2 Load (LOAD2) should be an Electronic Constant Current Mode Load capable of 0-2.5Adc at 1.2V

4.1.4 Oscilloscope

OSCILLOSCOPE

A Digital or Analog Oscilloscope can be used to measure the ripple voltage on VOUT1 or VOUT2. The Oscilloscope should be set for 1M Ω impedance, 20MHz Bandwidth, AC coupling, 1 μ s/division horizontal resolution, 10mV/division vertical resolution for taking output ripple measurements. TP3 and TP4 or TP18 and TP19 can be used to measure the output ripple voltages by placing the oscilloscope probe tip through TP3 or TP18 and holding the ground barrel to TP4 or TP19 as shown in [Figure 3](#). For a hands free approach, the loop in TP4 or TP19 can be cut and opened to cradle the probe barrel. Using a leaded ground connection may induce additional noise due to the large ground loop area.

4.1.5 Recommended Wire Gauge

V_{IN} to J1

The connection between the source voltage, VIN and J1 of HPA431 can carry as much as 5 Adc. The minimum recommended wire size is AWG #16 with the total length of wire less than 4 feet (2 feet input, 2 feet return).

J2 to LOAD1

The power connection between J2 of HPA431 and LOAD1 can carry as much as 1.5Adc. The minimum recommended wire size is AWG #18, with the total length of wire less than 2 feet (1 foot output, 1 foot return).

J3 to LOAD2

The power connection between J3 of HPA431 and LOAD2 can carry as much as 2.5Adc. The minimum recommended wire size is AWG #18, with the total length of wire less than 2 feet (1 foot output, 1 foot return).

4.1.6 Other

FAN

This evaluation module includes components that can get hot to the touch, because this EVM is not enclosed to allow probing of circuit nodes, a small fan capable of 200-400 lfm is recommended to reduce component surface temperatures to prevent user injury. The EVM should not be left unattended while powered. The EVM should not be probed while the fan is not running.

4.2 Equipment Setup

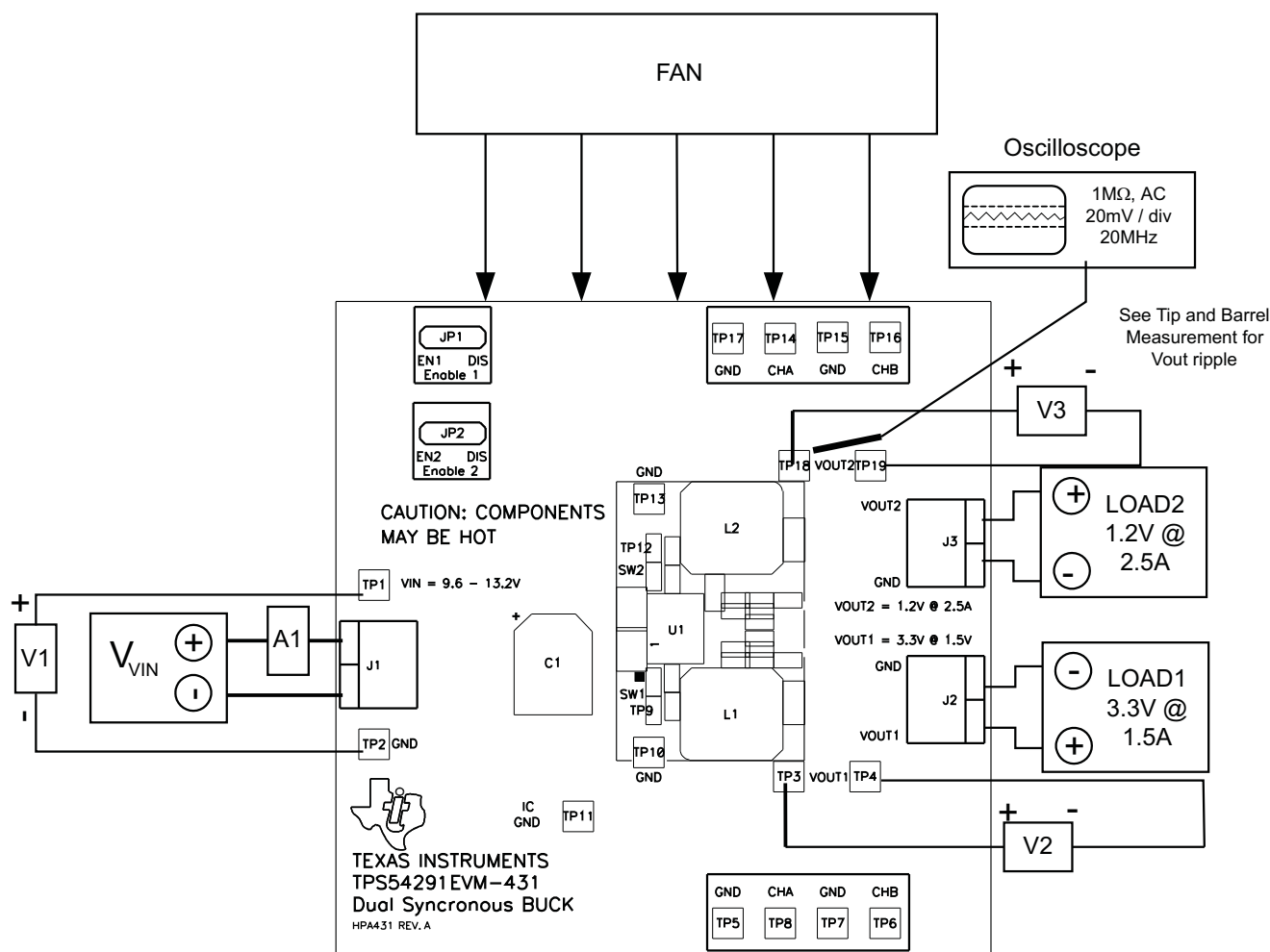
Shown in [Figure 2](#) is the basic test set up recommended to evaluate the TPS54291EVM-431. Note that although the return for J1, J2 and JP3 are the same system ground, the connections should remain separate as shown in [Figure 2](#).

4.2.1 Procedure

1. Working at an ESD workstation, make sure that any wrist straps, bootstraps or mats are connected referencing the user to earth ground before power is applied to the EVM. Electrostatic smock and safety glasses should also be worn.
2. Prior to connecting the DC input source, V_{IN}, it is advisable to limit the source current from V_{IN} to 2.0A

- maximum. Make sure V_{IN} is initially set to 0V and connected as shown in Figure 2.
3. Connect the ammeter A1 (0-5A range) between V_{IN} and J1 as shown in Figure 2.
 4. Connect voltmeter V1 to TP1 and TP2 as shown in Figure 2.
 5. Connect LOAD1 to J2 as shown in Figure 2. Set LOAD1 to constant current mode to sink 0A_{dc} before V_{IN} is applied.
 6. Connect voltmeter, V2 across TP3 and TP4 as shown in Figure 2.
 7. Connect LOAD2 to J3 as shown in Figure 2. Set LOAD2 to constant current mode to sink 0A_{dc} before V_{IN} is applied.
 8. Connect voltmeter, V3 across TP18 and TP19 as shown in Figure 2.
 9. Place Fan as shown in Figure 3 and turn on, making sure air is flowing across the EVM.

4.2.2 Diagram



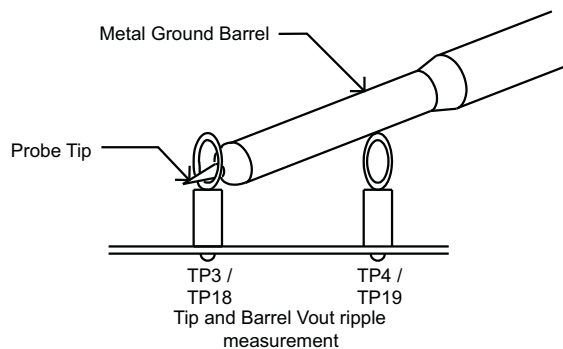


Figure 3. Output Ripple Measurement – Tip and Barrel using TP3 and TP4 or TP18 and TP19

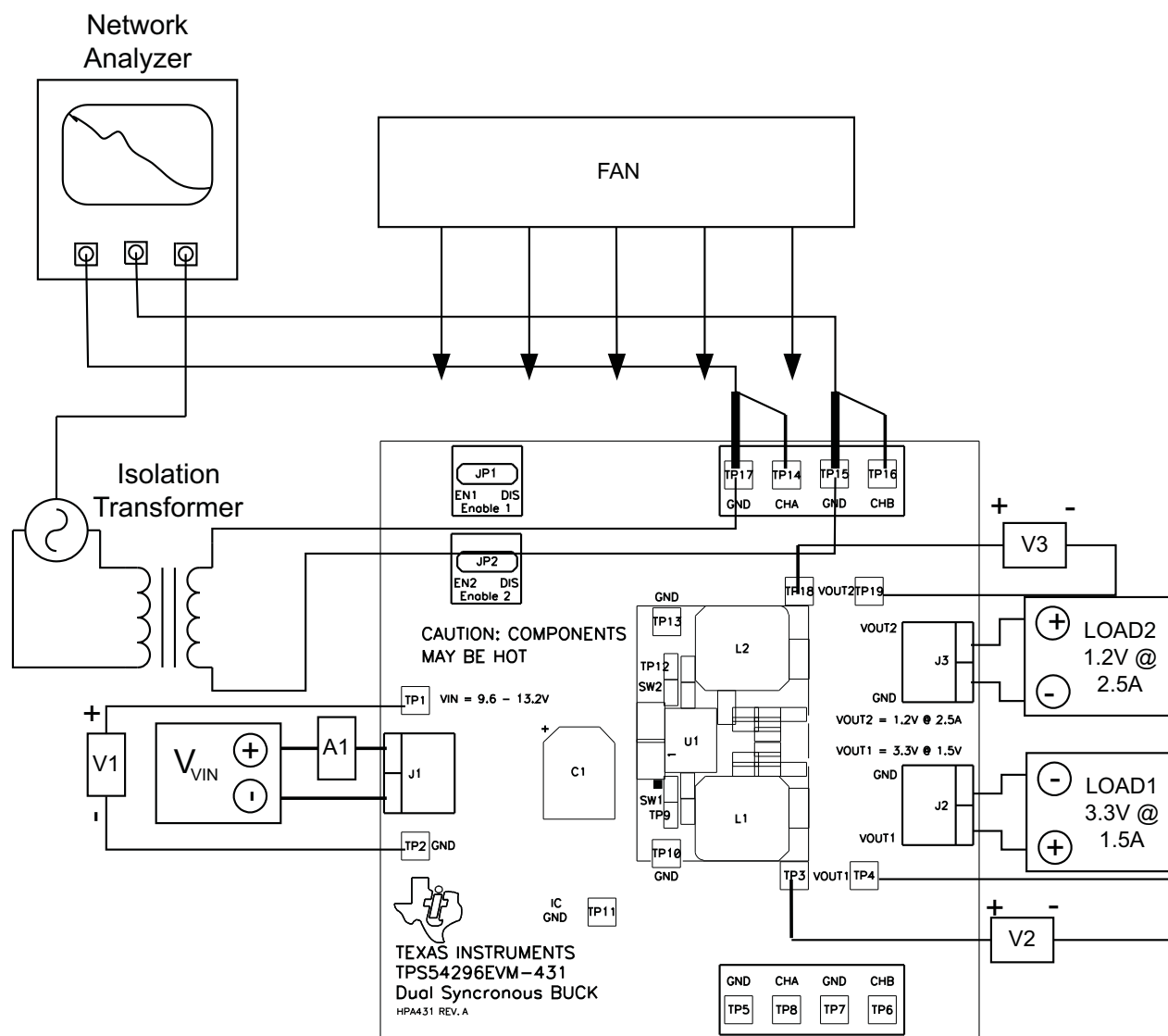


Figure 4. Control Loop Measurement Setup

4.3 Start Up / Shut Down Procedure

1. Increase V_{IN} from 0V to 12Vdc

2. Vary LOAD1 from 0 – 1.5Adc
3. Vary LOAD2 from 0 – 2.5Adc
4. Vary V_{IN} from 9.6Vdc to 13.2Vdc
5. Decrease V_{IN} to 0Vdc
6. Decrease LOAD1 to 0A
7. Decrease LOAD2 to 0A

4.4 Output Ripple Voltage Measurement Procedure

See Section 5.4 for more information on measuring output ripple.

1. Increase V_{IN} from 0V to 12Vdc
2. Adjust LOAD1 to desired load between 0Adc and 1.5Adc
3. Adjust LOAD2 to desired load between 0Adc and 2.5Adc
4. Adjust V_{IN} to desired load between 9.6Vdc and 13.2Vdc
5. Connect Oscilloscope Probe to TP3 and TP4 or TP18 and TP19 as shown in [Figure 3](#)
6. Measure Output Ripple
7. Decrease V_{IN} to 0Vdc
8. Decrease LOAD1 to 0A
9. Decrease LOAD2 to 0A

4.5 Control Loop Gain and Phase Measurement Procedure

1. Connect 1kHz–1MHz Isolation Transformer to TP6 and TP8 as show in [Figure 4](#)
2. Connect Input Signal Amplitude Measurement Probe (Channel A) to TP8 as shown in [Figure 4](#)
3. Connect Output Signal Amplitude Measurement Probe (Channel B) to TP6 as shown in [Figure 4](#)
4. Connect Ground Lead of Channel A and Channel B to TP5 and TP7 as shown in [Figure 4](#)
5. Inject 30mV or less signal across R1 through Isolation Transformer
6. Sweep Frequency from 1kHz to 1MHz with 10Hz or lower post filter

$$20 \times \text{LOG} \left(\frac{\text{ChannelB}}{\text{ChannelA}} \right)$$

7. Control Loop Gain can be measured by
8. Control Loop Phase is measured by the Phase difference between Channel A and Channel B
9. Control Loop for Channel 2 can be measured by making the following substitutions
 - (a) Change TP6 to TP16
 - (b) Change TP8 to TP14
 - (c) Change TP5 to TP17
 - (d) Change TP7 to TP15
10. Disconnect Isolation Transformer before making any other measurements (Signal Injection into Feedback may interfere with accuracy of other measurements)

4.6 Equipment Shutdown

1. Shut Down Oscilloscope
2. Shut down V_{IN}
3. Shut down LOAD1
4. Shut down LOAD2
5. Shut down FAN

5 TPS54291EVM-431 Typical Performance Data and Characteristic Curves

[Figure 5](#) through [Figure 7](#) present typical performance curves for the TPS54291EVM-431. Since actual performance data can be affected by measurement techniques and environmental variables, these curves are presented for reference and may differ from actual field measurements.

5.1 Efficiency

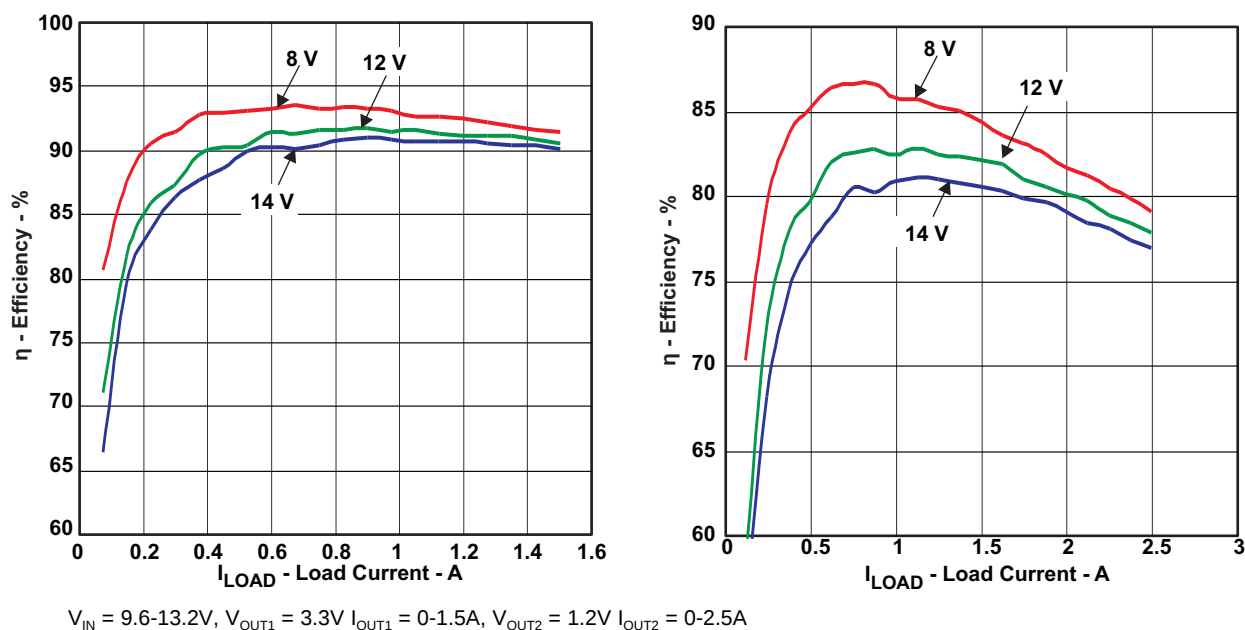


Figure 5. TPS54291EVM-431 Efficiency vs Load Current

5.2 Line and Load Regulation

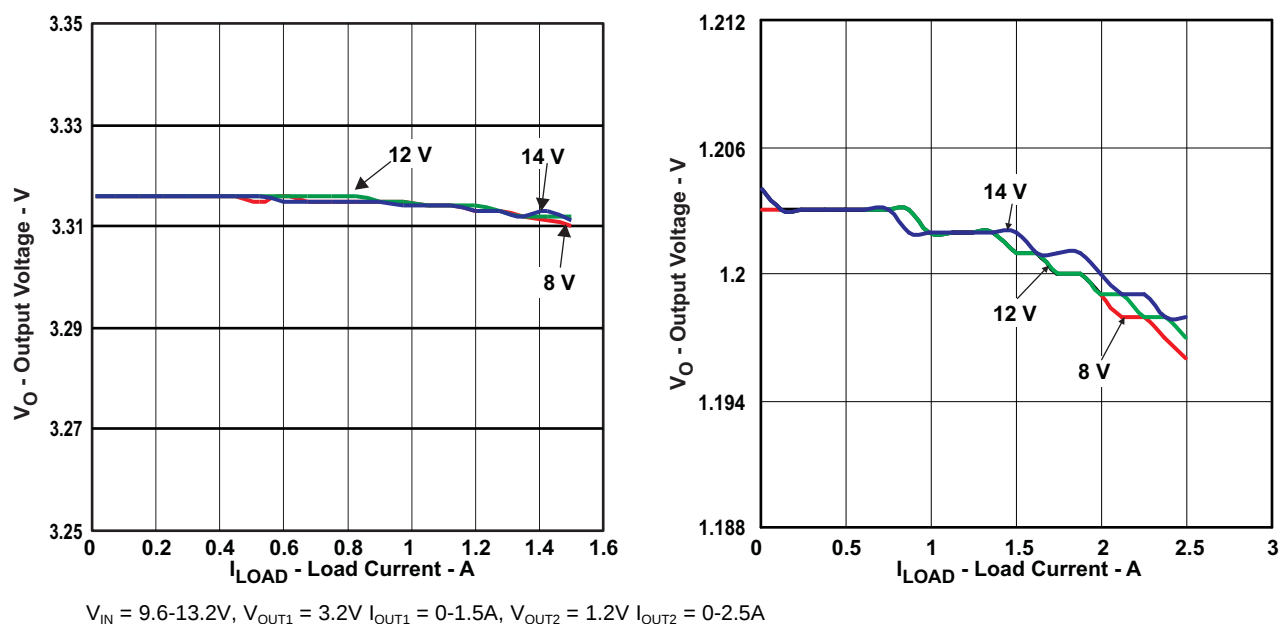
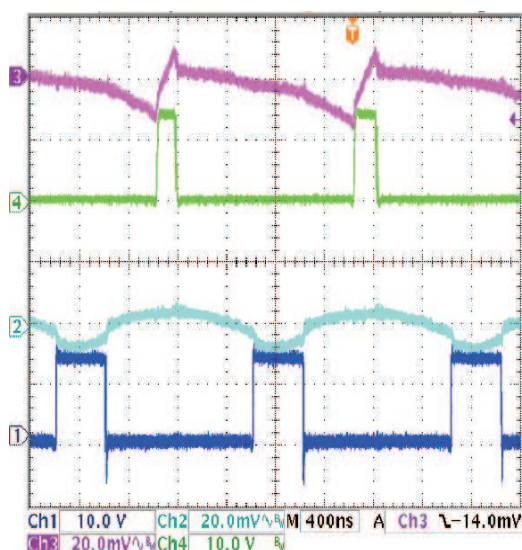


Figure 6. TPS54291EVM-431 Output Voltage vs Load Current

5.3 Switch Node and Output Voltage Ripple



$V_{IN} = 13.2V$, $V_{OUT1} = 3.3A$, $I_{OUT2} = 1.2V$ $I_{OUT2} = 2.5A$

Ch1: TP3 (VOUT1), Ch2: TP18 (VOUT2) Ch3: TP9 (SW1), Ch4: TP12 (SW2)

Figure 7. TPS54291EVM-431 Output Voltage Ripple

6 EVM Assembly Drawings and Layout

Figure 8 through Figure 13 show the designs of the TPS54291EVM-431 printed circuit board. The EVM has been designed using a 4-Layer, 2oz copper-clad circuit board 3.0" × 3.0" with all components in a 0.86" × 1.28" active area on the top side and all active traces to the top and bottom layers to allow the user to easily view, probe and evaluate the TPS54291 control IC in a practical double-sided application. Moving components to both sides of the PCB or using additional internal layers can offer additional size reduction for space constrained systems

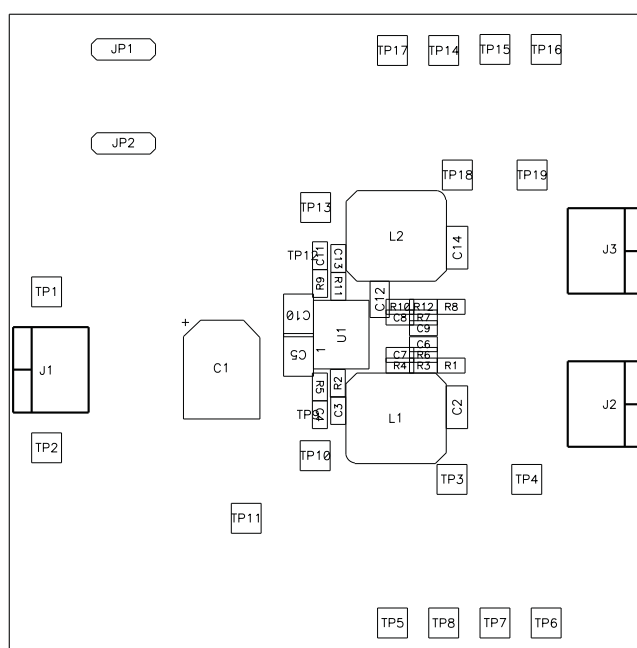


Figure 8. TPS54291EVM-431 Component Placement (Viewed from Top)

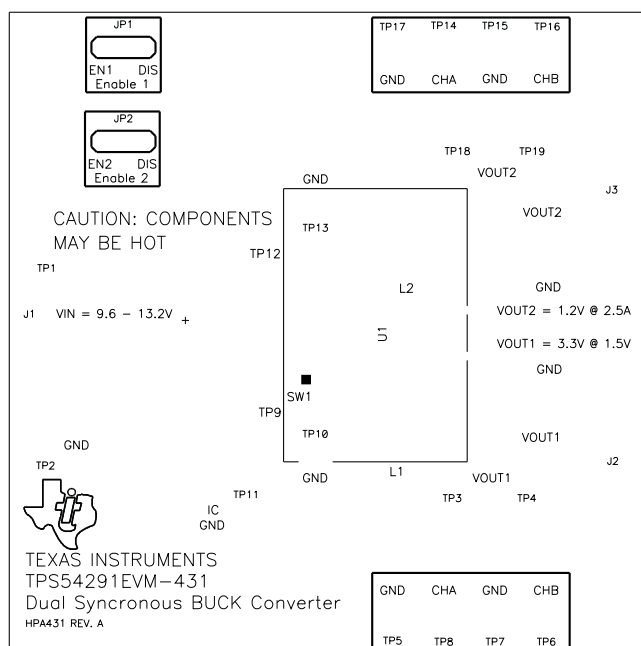


Figure 9. TPS54291EVM-431 Silkscreen (Viewed from Top)

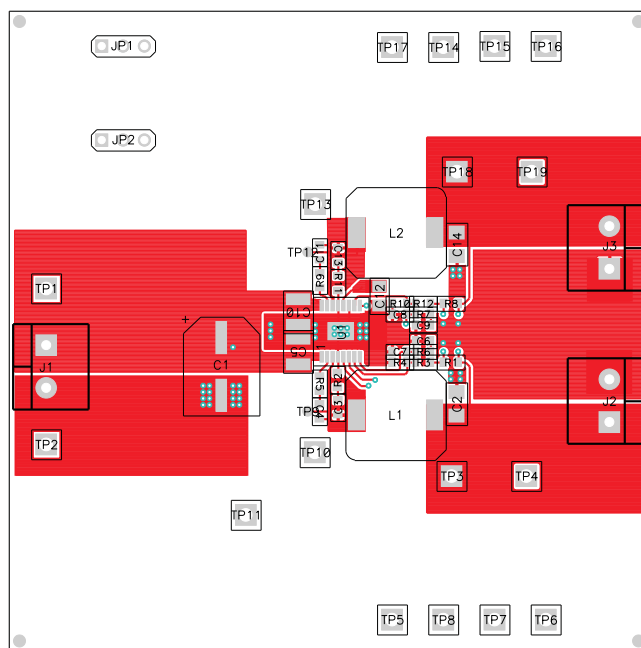


Figure 10. TPS54291EVM-431 Top Copper (Viewed from Top)

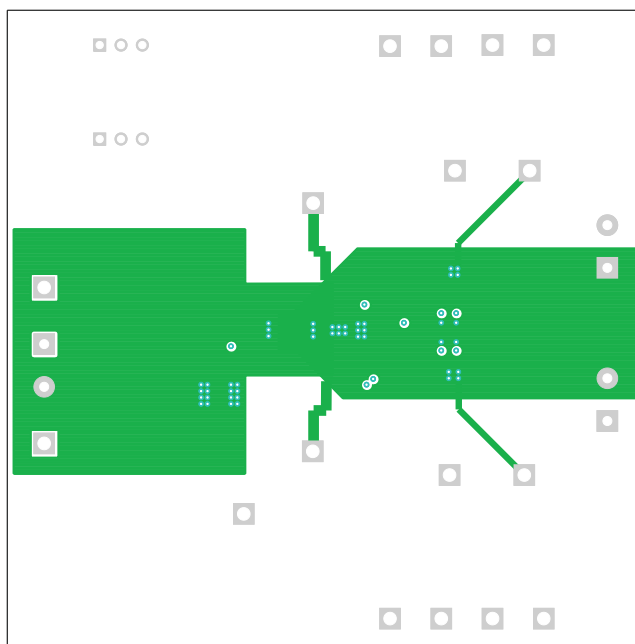


Figure 11. TPS54291EVM-431 Bottom Copper (X-Ray View from Top)

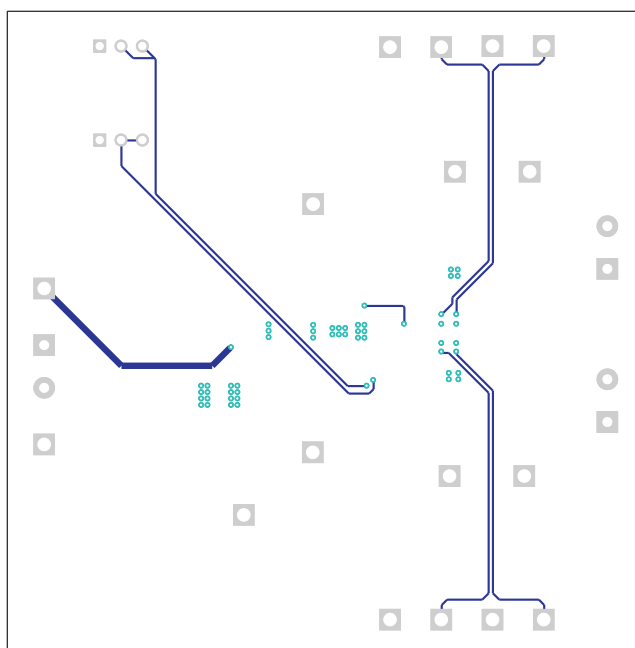


Figure 12. TPS54291EVM-431 Internal 1 (X-Ray View from Top)

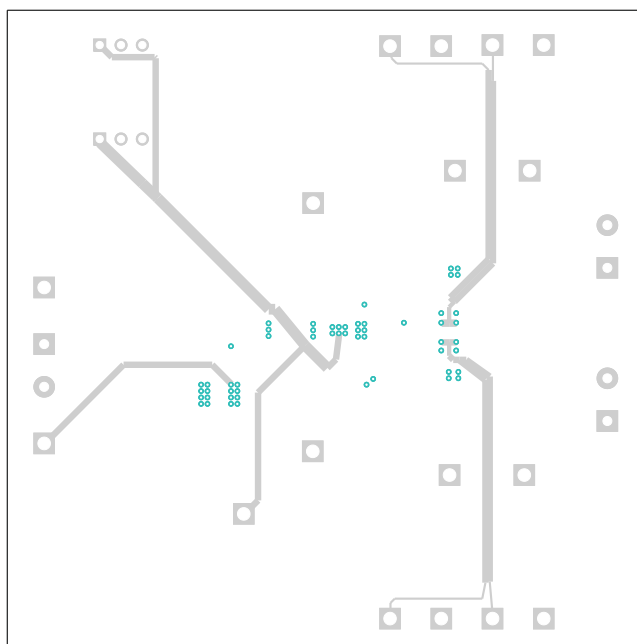


Figure 13. TPS54291EVM-431 Internal 2 (X-Ray View from Top)

7 List of Materials

Table 3 lists the EVM components as configured according to the schematic shown in Figure 1.

Table 3. TPS54291EVM-431 Bill of Materials

QTY	RefDes	Value	Description	Size	Part Number	MFR
1	C1	100 μ F	Capacitor, Aluminum, 25V, $\pm$ 20%	0.328 x 0.390 inch	EEEF1E101P	Panasonic
1	C12	4.7 μ F	Capacitor, Ceramic, 10V, X5R, 20%	0805	Std	Std
2	C2, C14	22 μ F	Capacitor, Ceramic, 6.3V, X5R, 20%	1206	C3216X5R0J226M	TDK
2	C3, C13	470 pF	Capacitor, Ceramic, 25V, X7R, 20%	0603	Std	Std
2	C4, C11	0.047 μ F	Capacitor, Ceramic, 25V, X7R, 20%	0603	Std	Std
2	C5, C10	10 μ F	Capacitor, Ceramic, 25V, X5R, 20%	1210	C3225X5R1E106M	TDK
1	C6	1.8 nF	Capacitor, Ceramic, 25V, X7R, 20%	0603	Std	Std
1	C7	15 pF	Capacitor, Ceramic, 25V, C0G, 20%	0603	Std	Std
1	C8	47 pF	Capacitor, Ceramic, 25V, C0G, 20%	0603	Std	Std
1	C9	1.2 nF	Capacitor, Ceramic, 25V, X7R, 20%	0603	Std	Std
3	J1, J2, J3	ED1609-ND	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	ED120/2DS	OST
2	JP1, JP2	PEC03SAAN	Header, 3-pin, 100mil spacing	0.100 inch x 3	PEC03SAAN	Sullins
1	L1	8.2 μ H	Inductor, SMT, 4.38A, 20 m Ω	0.402 x 0.394 inch	MSS1048-822L	Coilcraft
1	L2	3.3 μ H	Inductor, SMT, 4.38A, 20 m Ω	0.402 x 0.394 inch	MSS1048-332L	Coilcraft
2	R1, R8	51	Resistor, Chip, 1/16W, 5%	0603	Std	Std
1	R10	40.2 k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R2, R11	10	Resistor, Chip, 1/16W, 5%	0603	Std	Std
2	R3, R12	20.5 k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R4	6.49 k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R5, R9	0	Resistor, Chip, 1/16W, 5%	0603	Std	Std
1	R6	53.6 k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R7	18.7 k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	TP1, TP3, TP18 TP2, TP4, TP5, TP7, TP10, TP13, TP15	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
9	TP17, TP19, TP6, TP8, TP11, TP14	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone
5	TP16	5012	Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
0	TP9, TP12	None	Test point, 40 mil SMT	None	None	None
1	U1	TPS54291PWP	IC, 2.5/1.5A, 600Hz, Dual Output Fully Synchronous Buck Converter W/Integrated FET	CSP	TPS54291PWP	TI
2	–		Shunt, 100-mil, Black	0.100	929950-00	3M
1	–		PCB, 3 In x 3 In x 0.063 In		HPA431	Any

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